



Millenium Science Complex

New clean room: 10,000 sq. ft. class 100/1000

Support space : 6,500 sq. ft



Savannah_200

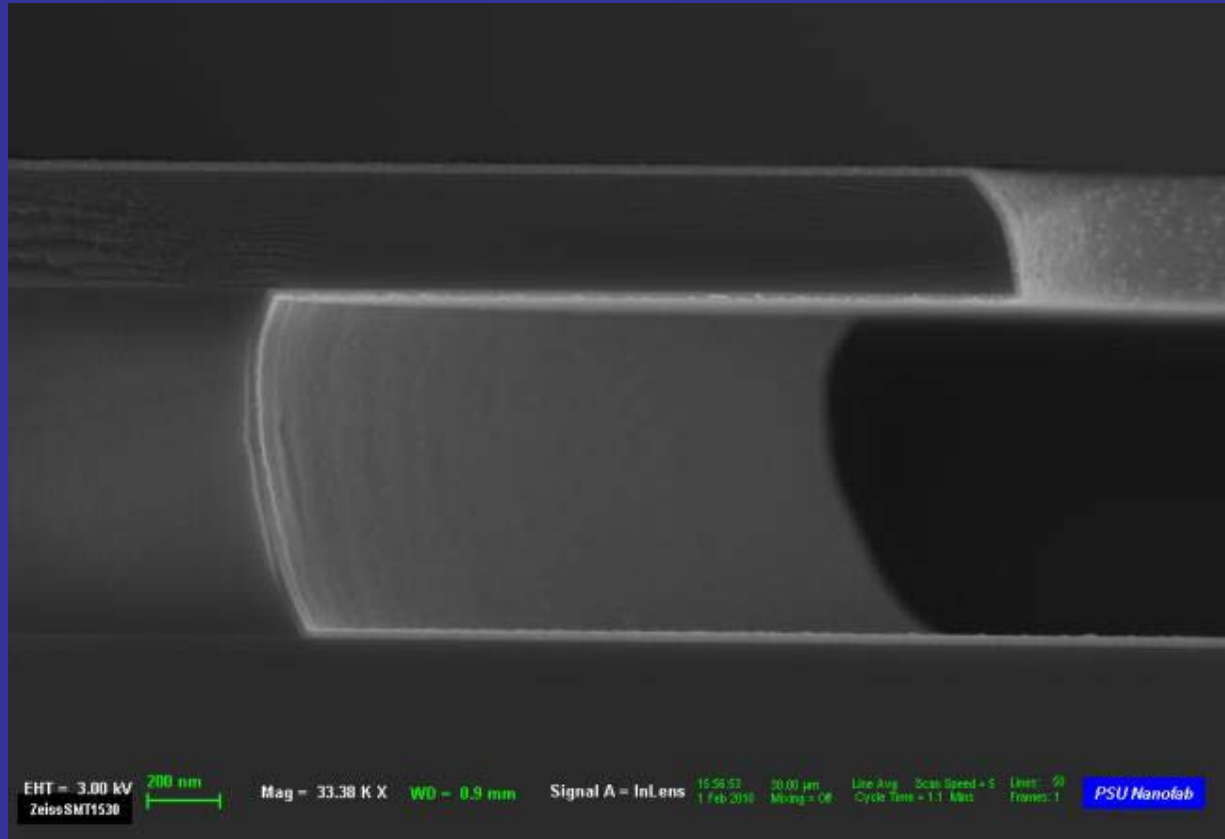
- Al_2O_3 (1.1 Å GPC @ 200°C)
- HfO_2 (1 Å GPC @ 110 °C)
- Ta_2O_5
- TiO_2 (0.457 Å GPC @ 150°C)
Titanium isopropoxide $\text{Ti}(\text{OiPr})_4$
Tetrakis(dimethylamino)titanium (TDMAT)
- ZrO_2
- ZnO_2 (stopped due to cross contamination)

Usage:08-present

- ~2,000 hrs per year ~23% based on 24/7
- \$50 per use for academic \$100 for industry before 3/1/12
\$75 per use for academic \$150 for industry after 3/1/12
- \$1 per 1nm
- \$20,000 per year

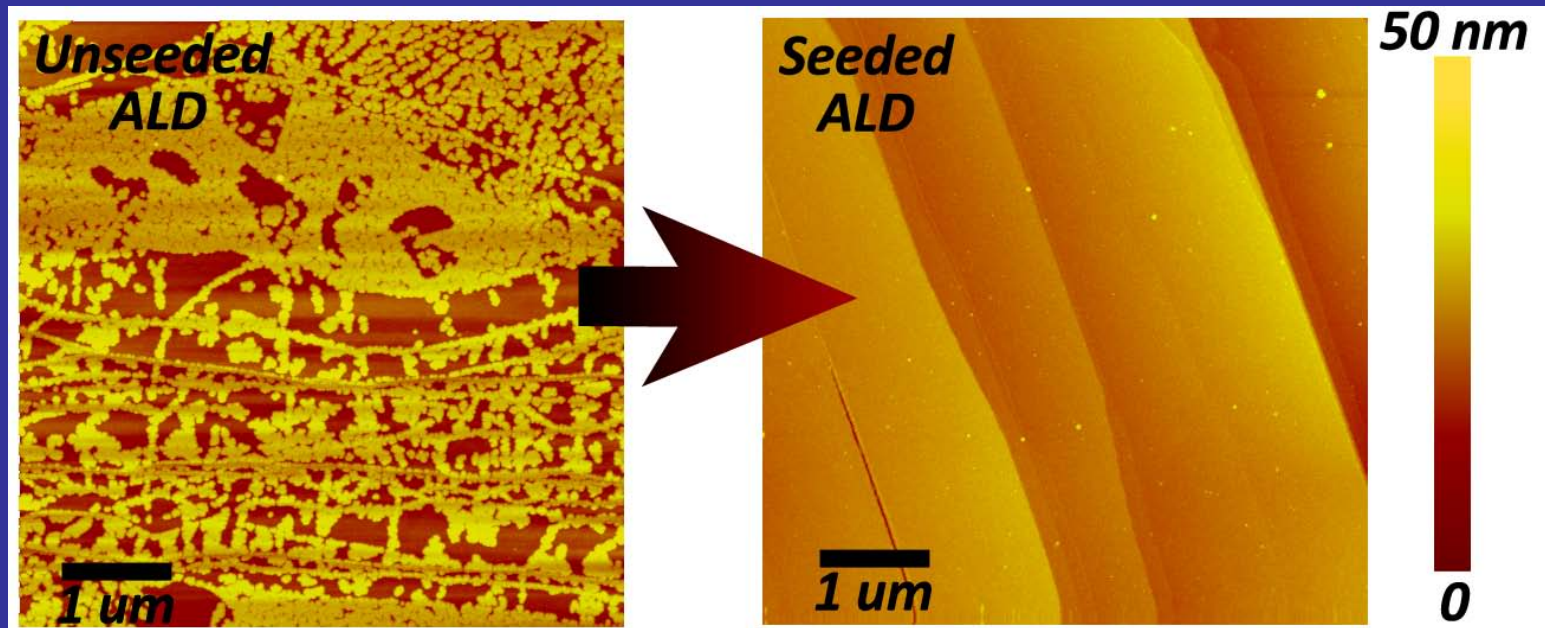


High conformity of ALD coating

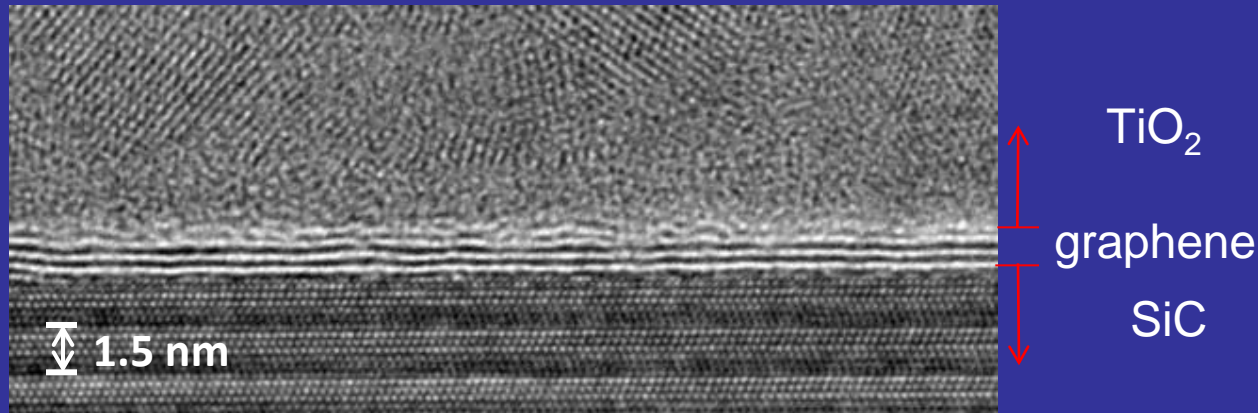


Cross-sectional FESEM view of 20 nm HfO₂

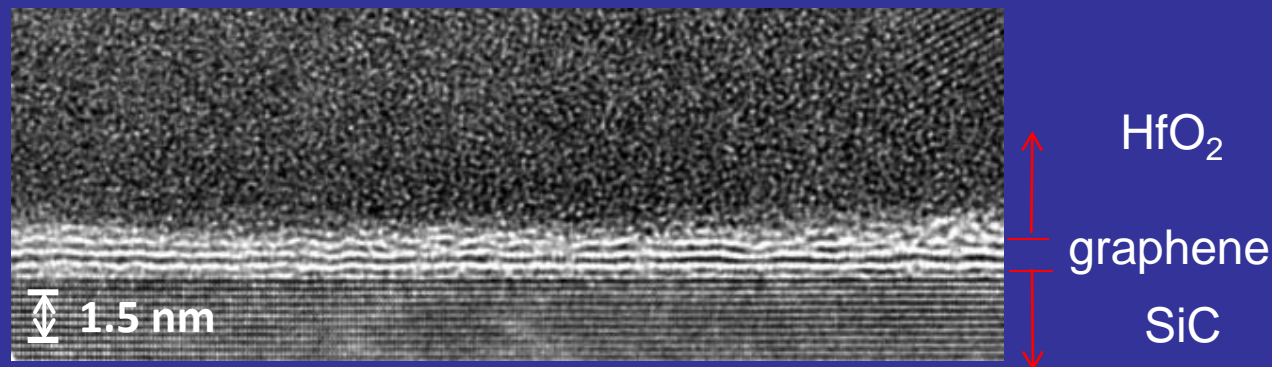
Comparison between seeded and unseeded ALD deposition on graphene by AFM



Cross-sectional TEM characterization

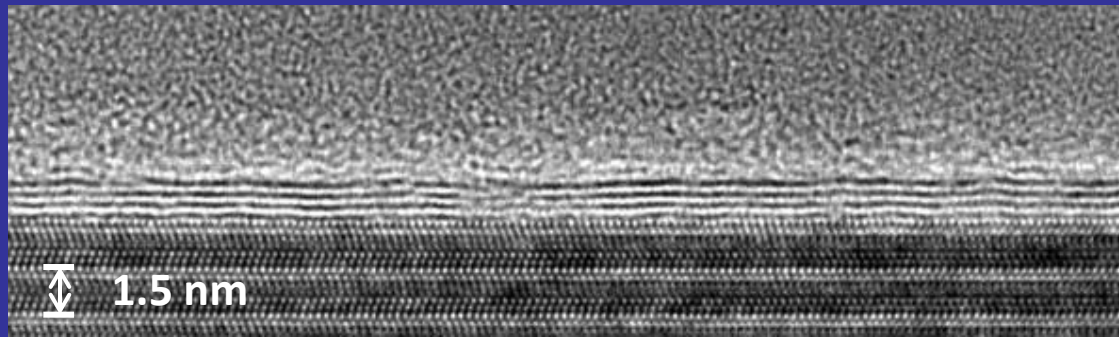


TiO₂ on Ti-seeded graphene @250°C



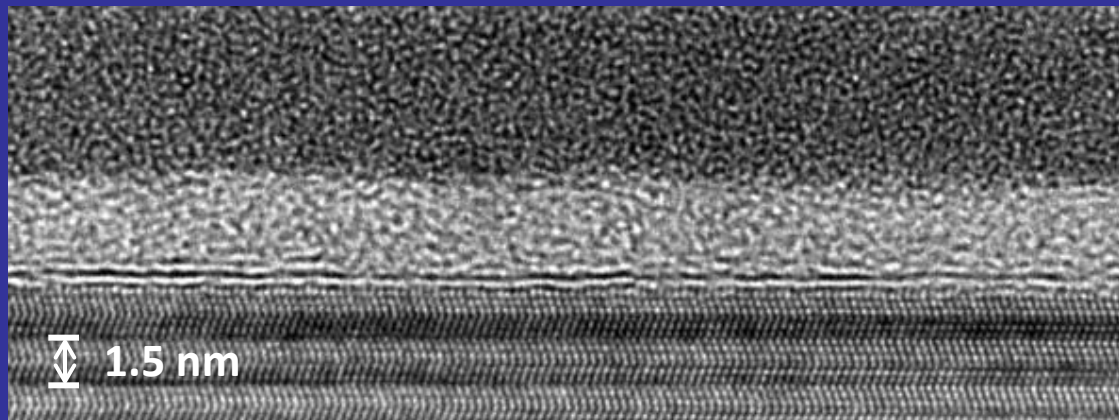
HfO₂ on graphene @110°C

Cross-sectional TEM characterization



↑ Al_2O_3
graphene
↓ SiC

Al_2O_3 on Al-seeded graphene @300°C

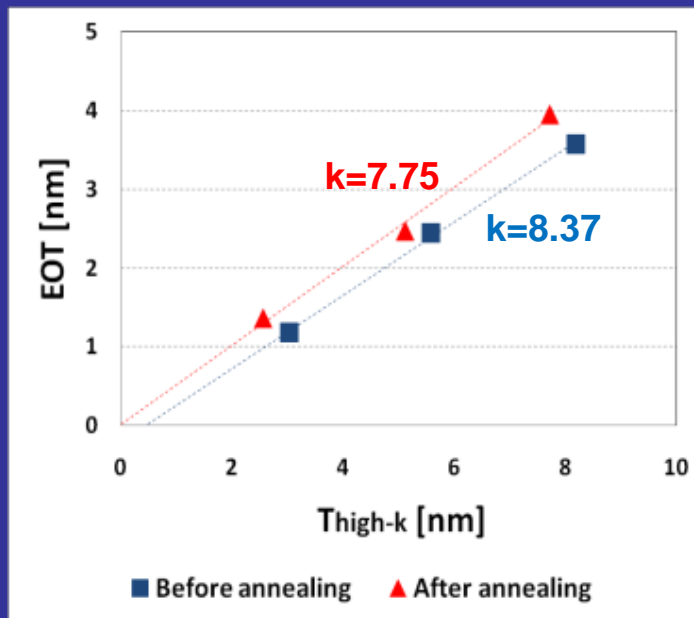


↑ Ta_2O_5
defective carbon region
graphene
↓ SiC

Ta_2O_5 on Ta-seeded graphene @150°C



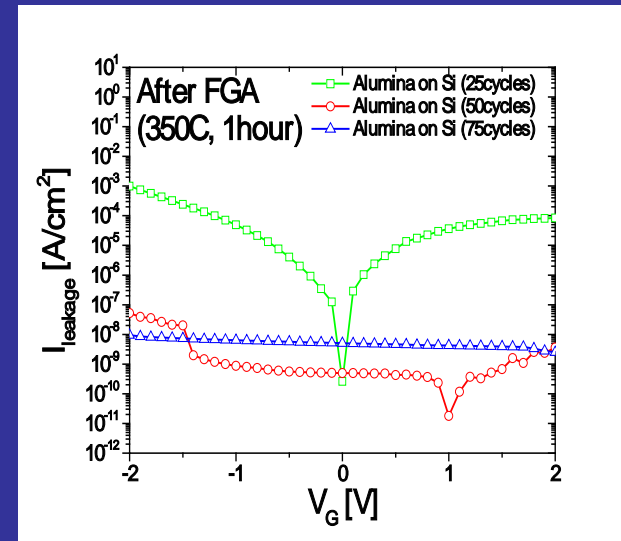
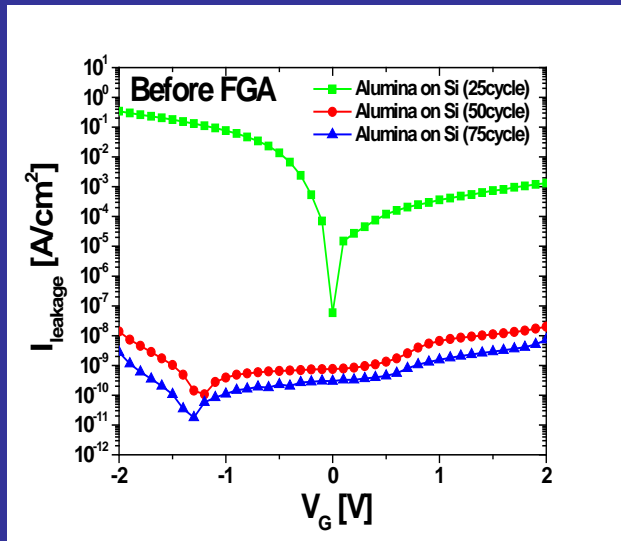
Electrical test of Al_2O_3 using MOSCAP



Dielectric constant : ~ 8

thinnest electrical oxide thickness (EOT) achieved till date is **12 A (1.2 nm)**

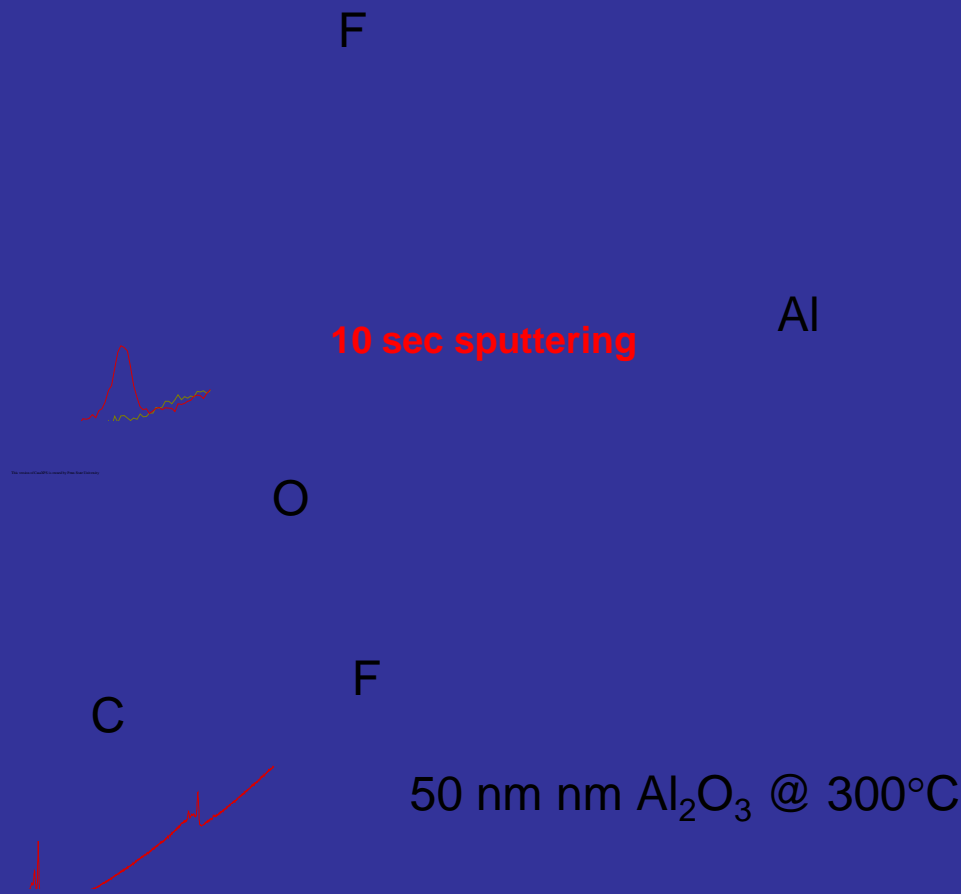
Si MOSCAP with alumina - Leakage



Leakage improves significantly for the 1.2 nm EOT gate stack by forming gas anneal at 350C for 1 hour



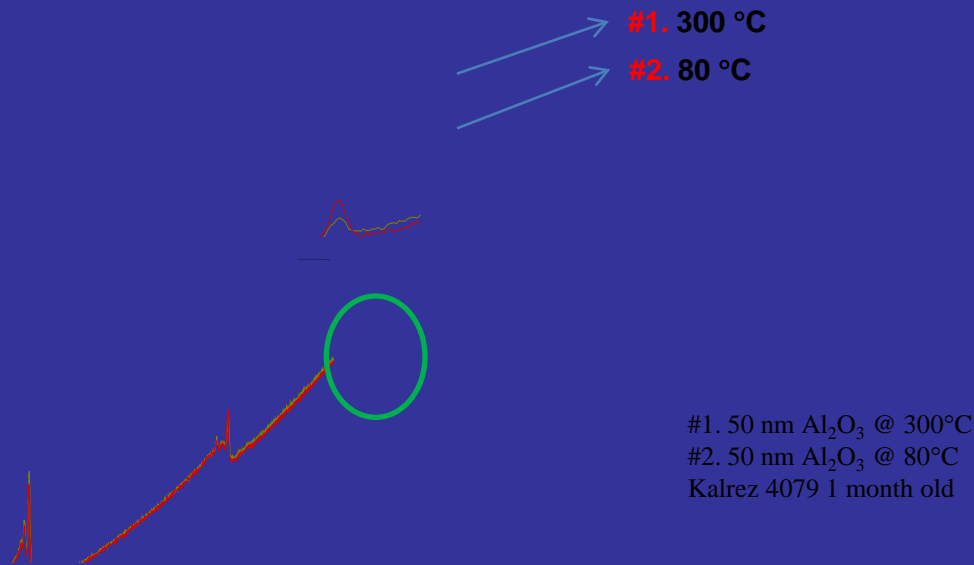
F outgassing characterization by Auger & XPS



F found in the top surface



F contamination depends on process temperature





F contamination depends on the age of O-ring

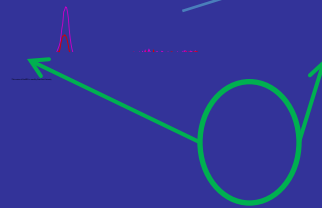
C

F

#1. 1 viton

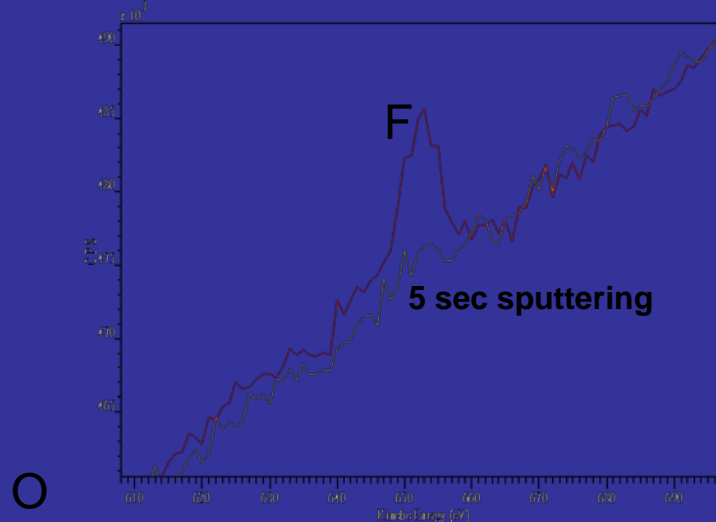
#2. Kalrez 4079 1 month old

#3. Kalrez 4079 11 month old

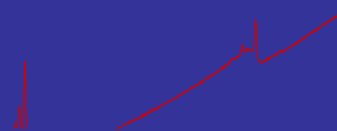




Auger analysis on Al₂O₃ sample prepared by Cambridge Nanotech



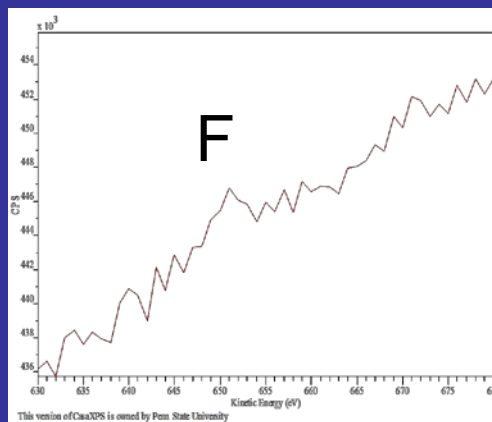
Al



40.9 nm Al₂O₃ , 250°C Cambridge Nanotech



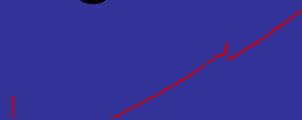
Auger analysis on SiO₂ sample prepared by Cambridge Nanotech



Al

O

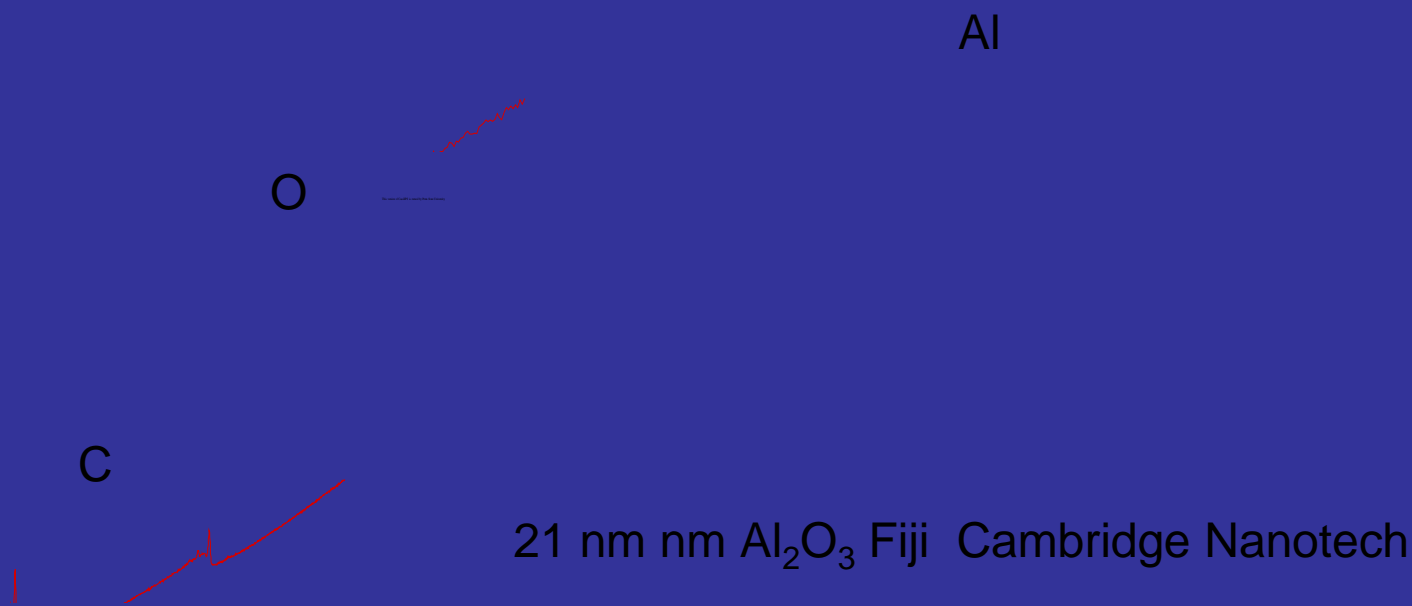
C



34.7nm SiO₂ grown at 250°C
Cambridge Nanotech



No F found in SiO₂ sample prepared by Fiji





Conclusions:

- F contamination can be found on all films prepared on Savannah systems
- The source of F comes from O-ring outgassing
- All high temperature O-rings made of fluorocarbon or perfluorocarbon materials have this issue
- F contamination depends on process temperature and O-ring age

Question:

How F contamination relates to electrical leakage?

Fact:

All films contains F on the surface (possibly not at the interface?), but not all films leaks.

F outgassing -> pitting on the lid ->
vacuum leaking -> electrical leakage



pitting occurs outside o-ring

O-ring



Vacuum maintenance

Leak checking regularly

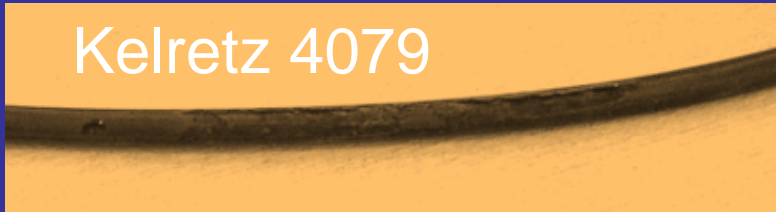
- Rate of rise 20-50 mtorr/min
- He leak detector

Two Al lids to swap regularly (every 2 or 3 months)

Making another stainless steel lid

Change O-ring regularly

Kelretz 4079



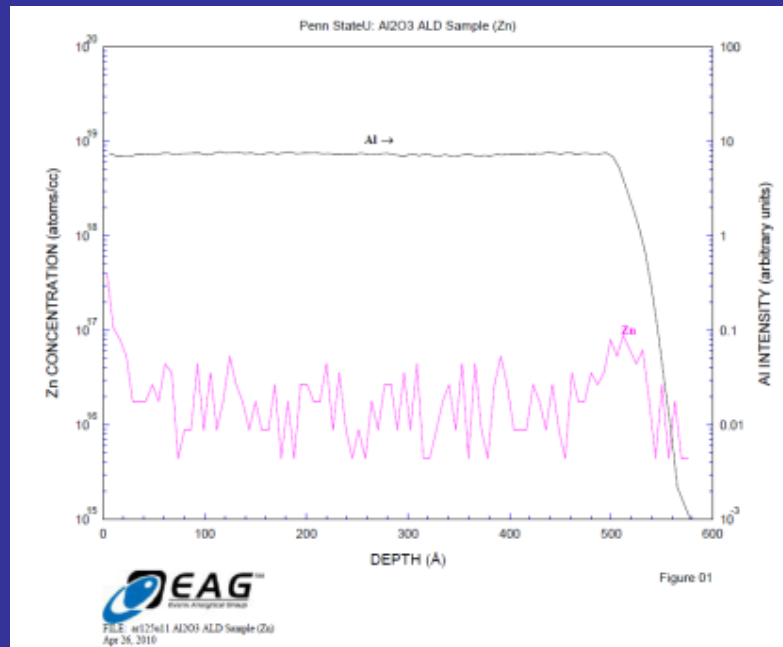


O-rings:

Viton	204 °C	cheap
Kelretz 4079	316°C	\$457.00
Kelretz 7075	327°C	\$457.00
FFKM 75 Black Perlast	327°C	\$325.24

(low outgassing, size G75TX,
Precision Polymer Engineering Ltd., UK)

Cross contamination: ZnO



SIMS analysis of Al₂O₃

Facts:

User complained about degraded optical and electrical properties after ZnO deposition

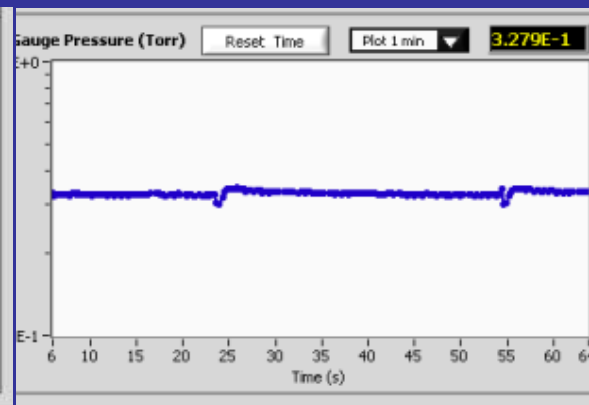
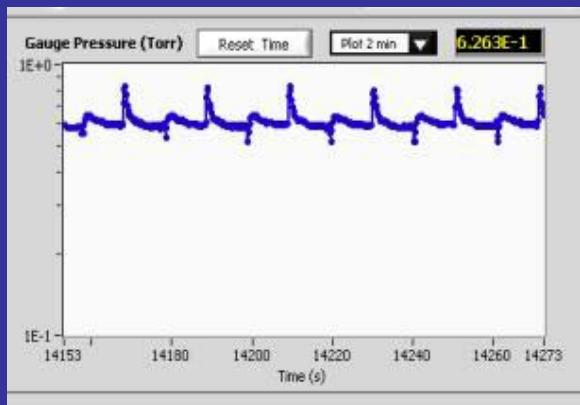
Solutions:

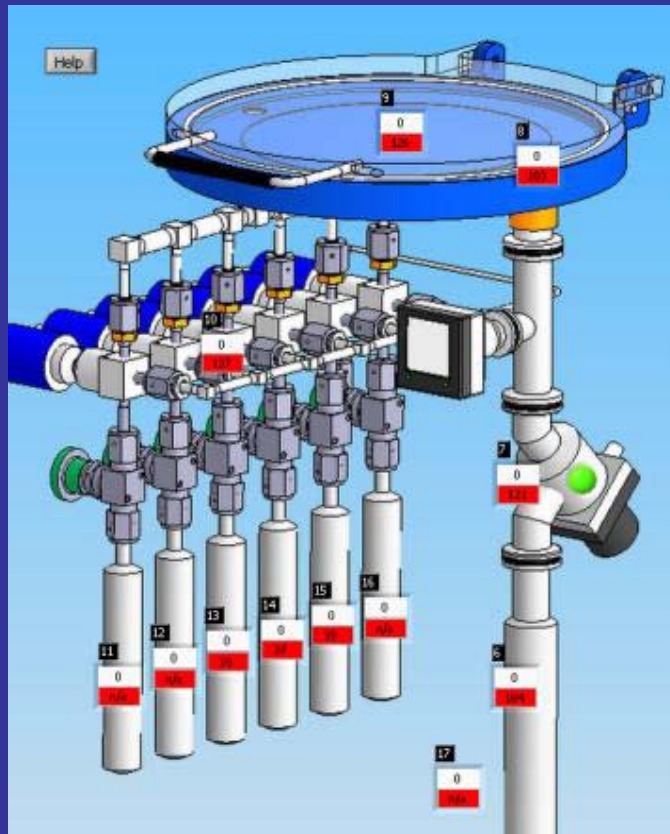
- Capping chamber by Al₂O₃
- Complete chamber cleaning
- Replacing manifold
- Stopped doing ZnO



Major issues

- **Electrical leakage**
 1. Cross contamination: ZnO
 2. Chamber leak -- O-ring etches Al lid(F outgassing)
- **Software crashes frequently due to RF noise?**
- **Self contamination**
 1. ALD valve
 2. Stop valve
 3. Gauge- pulse dips



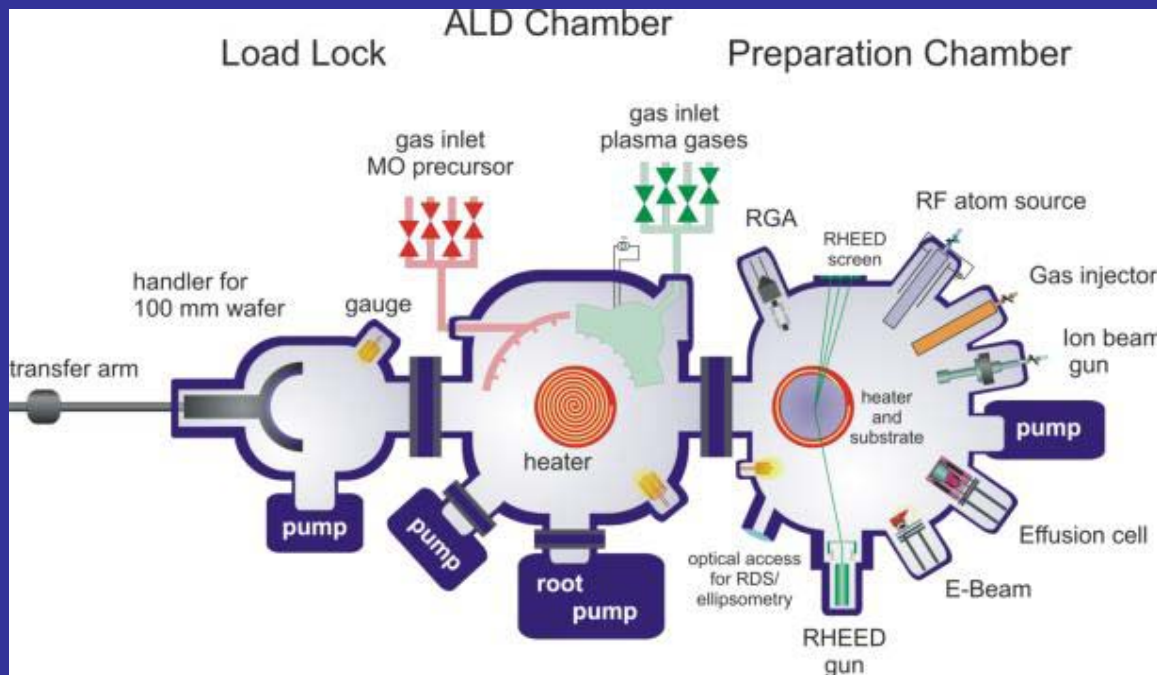


Major modifications

1. Expanded to 6-fold manifold
2. Made a second Al lid
2. To replace the Al lid w/ a stainless steel lid
3. To replace the existing black box w/ a silver box



Proposed dual chamber ALD tool



ALD growth chamber

- UHV compatible 10^{-8} torr
- Substrate heater up to 600°C
- thermal ALD & plasma enhanced ALD
- H_2 , N_2 and O_2 as plasma gas
- 6 precursor gas lines

Prep chamber:

- UHV compatible 10^{-8} torr
- Substrate heating to 600°C
- O_2 , H_2 , N_2 and Ar
- Effusion cell
- Ion beam gun
- RF atom source
- e-beam evaporator
- Gas injector

In situ monitoring capability options

- Differentially pumped RHEED system
- Ellipsometry
- DS/RAS optical access (normal incidence)